

Protecting LED Component Systems

We are global innovators in materials science.

Our team of engineers applies extensive industry knowledge about sub-assembly design to help suppress EMI crosstalk from automotive LED systems. And to help better safeguard against excessive heat.

Modern lighting systems are comprised of a power supply, a digital control board, and a light source - all ideally physically separated from each other.

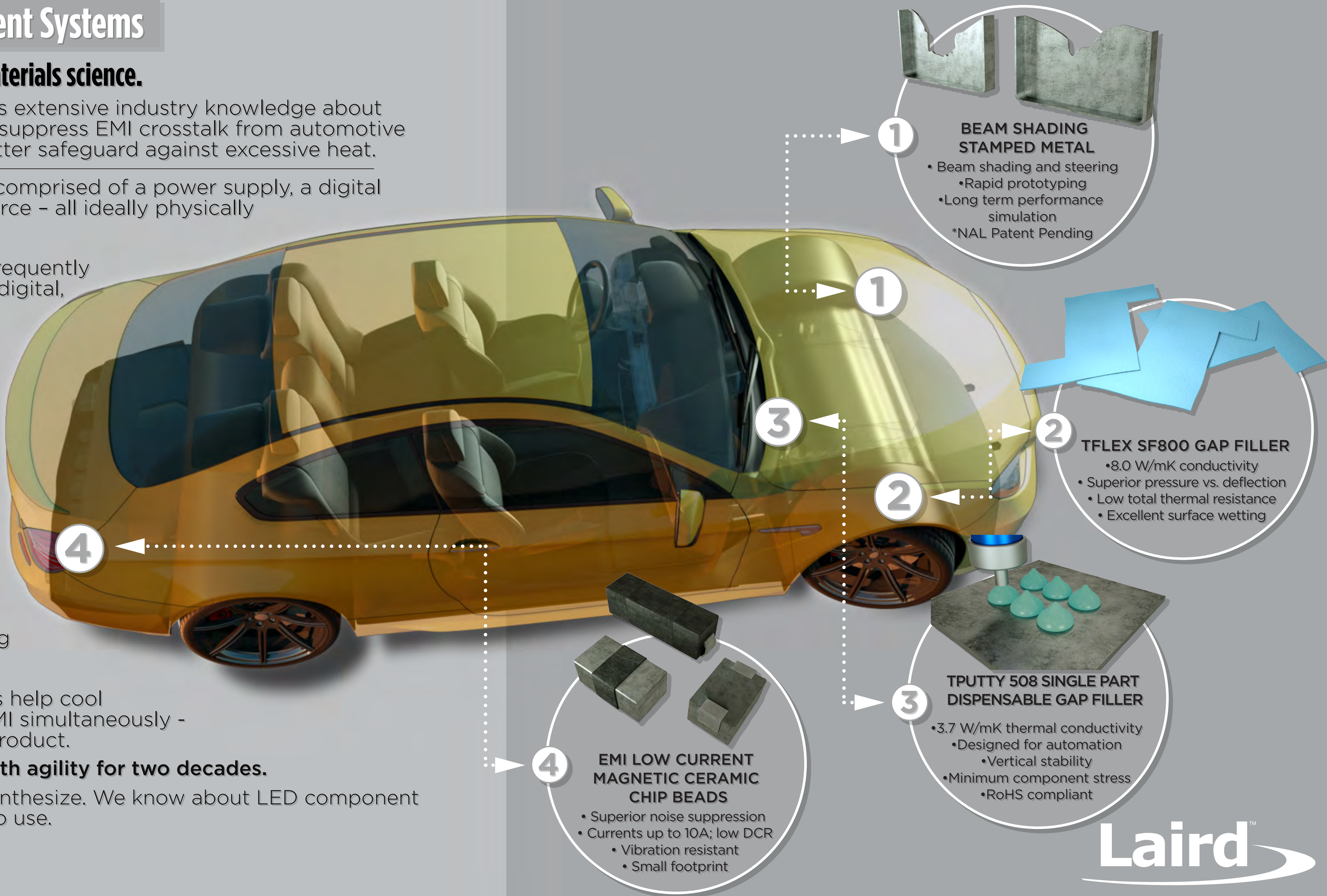
The pressure to reduce size frequently results in placing the analog, digital, and optical functions close together and not electrically isolated. This can create electrical crosstalk and can expose the optics to processing chemicals needed for the analog and digital circuits.

Laird has a complete line of non-silicone and low outgassing silicone-based pads, greases and dispensable products. Most importantly, we have the experience to advise you about deploying a variety of strategies.

Our multi-functional solutions help cool components and suppress EMI simultaneously - using a single space-saving product.

We are automotive grade. With agility for two decades.

We listen. We question. We synthesize. We know about LED component systems. Put our experience to use.



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BEAM SHADING STAMPED METAL

- Beam shading and steering
- Rapid prototyping
- Long term performance simulation
- *NAL Patent Pending

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TFLEX SF800 GAP FILLER

- 8.0 W/mK conductivity
- Superior pressure vs. deflection
- Low total thermal resistance
- Excellent surface wetting

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TPUTTY 508 SINGLE PART DISPENSABLE GAP FILLER

- 3.7 W/mK thermal conductivity
- Designed for automation
 - Vertical stability
- Minimum component stress
- RoHS compliant

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EMI LOW CURRENT MAGNETIC CERAMIC CHIP BEADS

- Superior noise suppression
- Currents up to 10A; low DCR
 - Vibration resistant
 - Small footprint



We Make Technology Work™

Protecting ADAS/Autonomous Driving Systems

Protecting LED Component Systems

TGREASE 2500

- 3.8 W/m-K thermal conductivity
- Silicone free thermal grease
- Ends migration issues
- Environmentally friendly

TPUTTY 607 ONE-PART DISPENSABLE GAP FILLER

- 6.4 W/m-K thermal conductivity
- Vertical reliability
- Low outgassing
- For PCB apps/lidar

Q-ZORB THERMOSET MICROWAVE ABSORBER

- Nomex™ or fiberglass honeycomb core
- Optimize insertion loss
- Optimize reflection loss
- For radar/radar brackets

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TPUTTY 508 SINGLE PART DISPENSABLE GAP FILLER

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- Vertical stability
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TGREASE 2500 THERMALLY CONDUCTIVE GREASE

- 3.8 W/mK thermal conductivity
- Environmentally friendly; silicone free
- Thoroughly wets out thermal surfaces
- No migration issues

TFLEX CR200 CURE-IN-PLACE GAP FILLER

- 2.0 W/mK thermal conductivity
- 2-part silicone base
- Low viscosity
- Ideal for large gap tolerances

SMD ELECTRONIC CONTACT

- Board/device interconnections
- Nickel, tin, gold, silver platings
- 0.13mm thickness

TPUTTY 506 SINGLE PART DISPENSABLE GAP FILLER

- 3.5 W/mK conductivity
- Non-curing/non-abrasive
- Transfers little/no pressure

TFLEX SF600 THERMALLY CONDUCTIVE GAP PAD

- 3.0 W/mK conductivity
- Silicone-free for sensitive apps
- 0.25mm to 3.56mm thickness
- In 0.010-inch increments
- RoHS compliant

TFLEX CR200 CURE-IN-PLACE GAP FILLER

- 2.0 W/mK thermal conductivity
- 2-part silicone base
- Low viscosity
- Ideal for large gap tolerances

TFLEX 400 HD THERMAL PAD

- 40 W/mK conductivity
- High deflection gap filler
- 1mm to 4mm thicknesses
- Excellent surface wetting

FABRIC-OVER-FOAM GASKET

- Plated, conductive fabrics/foams
- EMI shielding effectiveness >100dB
- Low surface resistivity
- RoHS compliant; Halogen free

MGV POWER INDUCTOR

- Lowest cost design goal
- Magnetic shielded
- High current/low profile
- Low DCR/high efficiency

EMI LOW CURRENT MAGNETIC CERAMIC CHIP BEAD

- Superior noise suppression
- Currents up to 10A; low DCR
- Vibration resistant
- Small footprint

TPUTTY 607 SINGLE PART DISPENSABLE GAP FILLER

- Low stress on components
- Designs for low cost
- Maximum thermal transfer
- PCB apps

LOW PROFILE SMD DC-DC POWER INDUCTOR

- Lowest cost design goal
- Maximum shielding
- Down to 1.8mm part height
- For space conscious designs

BROADBAND WIRE WOUND COMMON MODE CHOKE

- Nanocrystalline core
- Enables higher switching mode designs
- High power/high efficiency apps

Protecting Infotainment/Cluster Systems

Protecting EV/PHEV Battery Packs

Protecting EV Powertrain Electronics